

SMT inductors

SIMID series, SIMID 0603-C

Series/Type: B82496C

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SMT inductors, SIMID series

B82496C

SIMID 0603-C

SMD

Size 0603 (EIA) and/or 1608 (IEC) Rated inductance 1 nH to 220 nH Rated current 110 mA to 1800 mA



Construction

- Copper-plated ceramic core
- Laser-cut winding, epoxy-coated

Features

- Temperature range up to 150 °C
- High resonance frequency
- Close inductance tolerance
- Free of polarization effect
- High mechanical stability
- Qualified to AEC-Q200
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- RoHS-compatible

Applications

Resonant circuits, impedance matching for

- Multimedia
- Car access systems
- Wireless communication systems
- TPMS (Tire Pressure Monitoring System)
- GPS (Global Positioning System)
- Digital cameras

Terminals

- Base material Al₂O₃ ceramic with Cu layer
- Layer composition Ni, Sn (lead-free)
- Electro-plated

Marking

- No marking on component
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing unit

- 8-mm cardboard tape, wound on 180-mm Ø reel
- Bulk case on request
- Packing unit: 4000 pcs./reel



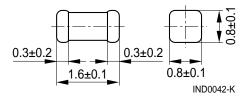
SMT inductors, SIMID series

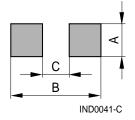
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Dimensional drawing and layout recommendation



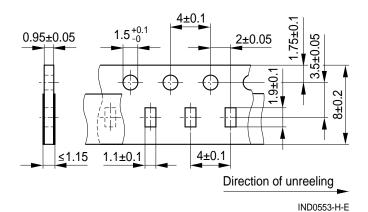


A	В	С
0.8 ±0.1	2.3 ±0.3	0.9 ±0.1

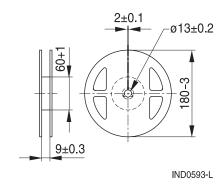
Dimensions in mm

Taping and packing

Cardboard tape



Reel



Dimensions in mm



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Technical data and measuring conditions

Rated inductance L _R	Measured with impedance analyzer Agilent 4291A and test fixture Agilent 16196A at frequency f _L , 0.1 V, 20 °C
Q factor Q _{min} , Q _{typ}	Measured with impedance analyzer Agilent 4291A and test fixture Agilent 16196A, Q _{min} measured at frequency f _Q , 20 °C
Rated temperature T _R	125 ℃
Rated current I _R	Maximum permissible DC with a temperature increase of \leq 15 K at rated temperature
Self-resonance frequency f _{res,min}	Measured with network analyzer Agilent 8720D, 20 °C
DC resistance R _{max}	Measured at 20 °C
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: (245 ± 5) °C, (5 ± 0.3) s Wetting of soldering area $\geq 95\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	260 °C, 40 s (as referenced in JEDEC J-STD 020C)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C +150 °C Packaged: -25 °C +40 °C, ≤ 75% RH
Weight	Approx. 4 mg



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Characteristics and ordering codes

$\overline{L_R}$	Tolerance	Q _{min}	Q _{typ} (at	f _L ; f _Q	I _R	R _{max}	f _{res,min}	Ordering code ¹⁾²⁾ (reel packing)
nH			800 MHz)	MHz	mA	Ω	GHz	(reer packing)
1.0	±0.3 nH ≙ A	7	60	100	1800	0.02	16	B82496C3109+000
1.2	±0.2 nH ≙ Z	8	60	100	1800	0.025	15	B82496C3129+000
1.5		8	50	100	1500	0.03	13	B82496C3159+000
1.8		12	50	100	1500	0.033	12	B82496C3189+000
2.2		14	50	100	1500	0.035	10	B82496C3229+000
2.7		14	40	100	1400	0.04	10	B82496C3279+000
3.3		14	40	100	1200	0.06	9	B82496C3339+000
3.9	±5% ≙ J	14	40	100	1100	0.065	8	B82496C3399+000
4.7	±0.2 nH ≙ Z	14	40	100	800	0.10	7	B82496C3479+000
5.6		14	40	100	700	0.15	6	B82496C3569+000
6.8	1	14	40	100	700	0.15	6	B82496C3689+000
8.2		14	40	100	650	0.18	6	B82496C3829+000
10	±5% ≙ J	14	40	100	600	0.20	5	B82496C3100+000
12	±2% ≙ G	14	40	100	450	0.35	5	B82496C3120+000
15		14	40	100	420	0.40	4.5	B82496C3150+000
18		14	40	100	400	0.45	4.0	B82496C3180+000
22		14	40	100	380	0.50	4.0	B82496C3220+000
27		14	35	100	360	0.55	3.0	B82496C3270+000
33		14	35	100	350	0.60	3.0	B82496C3330+000
39		14	35	100	300	0.80	2.5	B82496C3390+000
47		14	35	100	270	0.95	2.5	B82496C3470+000
56		14	35	100	250	1.2	2.5	B82496C3560+000
68		14	35	100	230	1.3	2.0	B82496C3680+000
82		14	35	100	220	1.5	2.0	B82496C3820+000
100		14	30	100	200	1.8	1.8	B82496C3101+000
120		5	30	25.2	160	3.0	1.8	B82496C3121+000
150		5	30	25.2	130	5.0	1.6	B82496C3151+000
180		4	25	25.2	120	6.0	1.4	B82496C3181+000
220		4	25	25.2	110	7.0	1.3	B82496C3221+000

Special versions on request.

Higher currents possible at temperatures <T_R on request.

Sample kit available (see also chapter "Sample kits". Ordering code: B82496X001

¹⁾ Replace the + by the code letter for the required inductance tolerance.

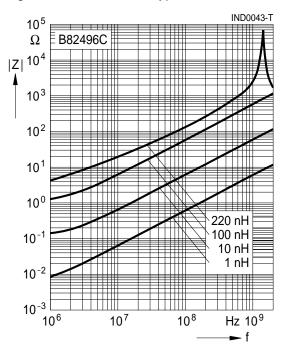
²⁾ For bulk case the last digit has to be a »1 «. Example: B82496C3109A001



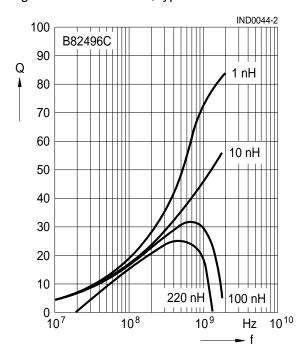
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Impedance |Z| versus frequency f

measured with impedance analyzer Agilent 4291A/16196A, typical values at 20 °C

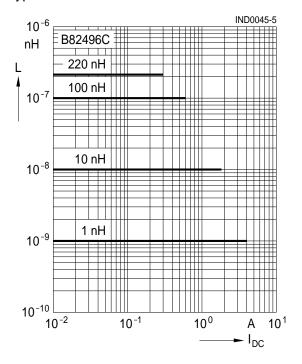


Q factor versus frequency f measured with impedance analyzer Agilent 4291A/16196A, typical values at 20 °C



SMD

Inductance L versus DC load current I_{DC} measured with LCR meter Agilent 4275A, typical values at 20 °C



Current derating I_{op}/I_R versus ambient temperature T_A (rated temperature $T_R = 125$ °C)

IND0046-L-E 1.2 B82496C I_{op} 1.0 8.0 0.6 0.4 0.2 20 40 60 80 100 120 °C 160 -T_A



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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